

Number	Hits	Search Text	IP	Time stamp
-	7	356/614-624.ccls. and semiconductor wafer and line adj beam	USPAT; US-PGPHB; EPIC; IPIC; PERCENT; IBM TIP	2003/03/19 14:17
-	55	356/614-624.ccls. and semiconductor wafer and line board beam	USPAT; US-PGPHB; EPIC; IPIC; PERCENT; IBM TIP	2003/03/19 14:47
-	71	356/614-624.ccls. and semiconductor wafer and slit with beam	USPAT; US-PGPHB; EPIC; IPIC; PERCENT; IBM TIP	2003/03/19 11:06
-	10	382/151.ccls. and line board beam	USPAT; US-PGPHB; EPIC; IPIC; PERCENT; IBM TIP	2003/03/19 11:02
-	17	382/151.ccls. and semiconductor or wafer) and slit	USPAT; US-PGPHB; EPIC; IPIC; PERCENT; IBM TIP	2003/03/19 11:44
-	93	356/614-624.ccls. and semiconductor wafer) and slit	USPAT; US-PGPHB; EPIC; IPIC; PERCENT; IBM TIP	2003/03/19 11:06
-	4	356/614-624.ccls. and semiconductor wafer) and slit and gradient	USPAT; US-PGPHB; EPIC; IPIC; PERCENT; IBM TIP	2003/03/19 11:09
-	19	356/614-624.ccls. and semiconductor wafer) and slit and gradient	USPAT; US-PGPHB; EPIC; IPIC; PERCENT; IBM TIP	2003/03/19 14:17
-	149	382/151.ccls. and semiconductor or wafer)	USPAT	2003/03/19 11:45
-	15	382/151.ccls. and semiconductor or wafer) and waveform	USPAT	2003/03/19 11:46
-	11	382/151.ccls. and (semiconductor or wafer) and waveform and coordinate	USPAT	2003/03/19 11:46
-	6	382/151.ccls. and (semiconductor or wafer) and waveform and coordinate and mask	USPAT	2003/03/19 11:48
-	1	382/151.ccls. and (semiconductor or wafer) and waveform and gradient and gradation)	USPAT	2003/03/19 12:09
-	31	382/151.ccls. and (semiconductor or wafer) and (mask) near4 image	USPAT	2003/03/19 12:11
-	22	356/614-624.ccls. and semiconductor wafer) and gradient and coordinate	USPAT	2003/03/19 12:19
-	43	350/559.38.ccls. and semiconductor wafer)	USPAT; US-PGPHB; EPIC; IPIC; PERCENT; IBM TIP	2003/03/19 14:15
-	39	350/559.38.ccls. and semiconductor wafer)	USPAT	2003/03/19 14:26
-	27	350/559.38.ccls. and semiconductor wafer) and range	USPAT	2003/03/19 14:26

